

Fab notes:

- 1. Material: 0.063" FR-4 glass epoxy, 1 oz copper
 2. This is a 2-layer PCB
 3. Route to indicated dimensions +/- 0.01"
 4. Minimum lines 0.05", spaces 0.010"
 5. Soldermask over bare copper, green color, both sides
 6. Remove silkscreen from solermask opening areas
 7. Silkscreen ledgend comp side, white
 8. All holes plated through 0.001" minimum unless specified
 9. Hole diameters after plating, +/- 0.004"
 10. Minimum plated hole size 0.032"
 11. May change silkscreen width per process requirements
 12. May change soldermask openings per pocess requirements

DRILL DRAWING

TOP SILKSCREEN

DRILL PLAN				
SYM	SIZE	TOL.	CNT	PLATE
M	0.032 in	+/-0.004 in	74	Yes
Ø	0.039 in	+/-0.004 in	4	Yes
Φ	0.040 in	+/-0.004 in	70	Yes
Ø	0.051 in	+/-0.004 in	24	Yes
Ø	0.066 in	+/-0.004 in	11	Yes
Ø	0.087 in	+/-0.004 in	16	Yes
9	0.156 in	+/-0.004 in	4	No

TOTAL 203 199

Drill file will contain one extra of each drill, placed in above diagram.